

RELIABILITY REPORT  
FOR  
**MAX253xxA**  
PLASTIC ENCAPSULATED DEVICES

January 30, 2003

**MAXIM INTEGRATED PRODUCTS**

120 SAN GABRIEL DR.

SUNNYVALE, CA 94086

Written by



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Reviewed by



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## Conclusion

The MAX253 successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

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### I. Device Description

#### A. General

The MAX253 is a monolithic oscillator/power-driver, specifically designed to provide isolated power for an isolated RS-485 or RS-232 data interface. It drives a center-tapped transformer primary from a 5V or 3.3V DC power supply. The secondary can be wound to provide any isolated voltage needed at power levels up to 1W.

The MAX253 consists of a CMOS oscillator driving a pair of N-channel power switches. The oscillator runs at double the output frequency, driving a toggle flip-flop to ensure 50% duty cycle to each of the switches. Internal delays are arranged to ensure break-before-make action between the two switches.

The SD pin puts the entire device into a low-power shutdown state, disabling both the power switches and oscillator.

#### B. Absolute Maximum Ratings

<u>Item</u>	<u>Rating</u>
Supply Voltage ( $V_{CC}$ )	-0.3V to +7V
Control Input Voltages (SD, FS)	-0.3V to ( $V_{CC} + 0.3V$ )
Output Switch Voltage (D1, D2)	12V
Peak Output Switch Current (D1, D2)	1A
Average Output Switch Current (D1, D2)	200mA
Continuous Power Dissipation ( $T_A = +70^{\circ}C$ )	
8 Lead Plastic DIP	727mW
8 Lead SO	471mW
8 Lead $\mu$ MAX	330mW
Derates above $+70^{\circ}C$ )	
8 Lead Plastic DIP	9.09mW/ $^{\circ}C$
8 Lead SO	5.88mW/ $^{\circ}C$
8 Lead $\mu$ MAX	4.10mW/ $^{\circ}C$
Operating Temperature Ranges	
MAX253C__	0 $^{\circ}C$ to $+70^{\circ}C$
MAX253E__	-40 $^{\circ}C$ to $+85^{\circ}C$
Junction Temperatures	
MAX253C__/_E__	+150 $^{\circ}C$
Storage Temperature Range	-65 $^{\circ}C$ to +160 $^{\circ}C$
Lead Temperature (soldering, 10sec)	+300 $^{\circ}C$

## II. Manufacturing Information

A. Description/Function:	Transformer Driver for Isolated RS-485 Interface
B. Process:	M5 (SMG – 5 micron silicon gate CMOS)
C. Number of Device Transistors:	31
D. Fabrication Location:	Oregon, USA
E. Assembly Location:	Philippines, Malaysia or Thailand
F. Date of Initial Production:	January, 1994

## III. Packaging Information

A. Package Type:	8-Pin PDIP	8-Pin SO	8-Pin uMAX
B. Lead Frame:	Copper	Copper	Copper
C. Lead Finish:	Solder Plate	Solder Plate	Solder Plate
D. Die Attach:	Silver-filled Epoxy	Silver-filled Epoxy	Silver-filled Epoxy
E. Bondwire:	Gold (1.3 mil dia.)	Gold (1.3 mil dia.)	Gold (1.3 mil dia.)
F. Mold Material:	Epoxy with silica filler	Epoxy with silica filler	Epoxy with silica filler
G. Assembly Diagram:	# 05-1901-0043	# 05-1901-0044	# 05-1901-0046
H. Flammability Rating:	Class UL94-V0	Class UL94-V0	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard JESD22-112:	Level 1		

## IV. Die Information

A. Dimensions:	58 x 85 mils
B. Passivation:	Si <sub>3</sub> N <sub>4</sub> /SiO <sub>2</sub> (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Aluminum/Si (Si = 1%)
D. Backside Metallization:	None
E. Minimum Metal Width:	5 microns (as drawn)
F. Minimum Metal Spacing:	5 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO <sub>2</sub>
I. Die Separation Method:	Wafer Saw

## V. Quality Assurance Information

- A. Quality Assurance Contacts: Jim Pedicord (Reliability Lab Manager)  
Bryan Preeshl (Executive Director)  
Kenneth Huening (Vice President)
- B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.  
0.1% For all Visual Defects.
- C. Observed Outgoing Defect Rate: < 50 ppm
- D. Sampling Plan: Mil-Std-105D

## VI. Reliability Evaluation

### A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in **Table 1**. Using these results, the Failure Rate ( $\lambda$ ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4389 \times 240 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

▲  
Temperature Acceleration factor assuming an activation energy of 0.8eV

$$\lambda = 4.52 \times 10^{-9}$$

$$\lambda = 4.52 \text{ F.I.T. (60\% confidence level @ 25°C)}$$

This low failure rate represents data collected from Maxim's reliability monitor program. In addition to routine production Burn-In, Maxim pulls a sample from every fabrication process three times per week and subjects it to an extended Burn-In prior to shipment to ensure its reliability. The reliability control level for each lot to be shipped as standard product is 59 F.I.T. at a 60% confidence level, which equates to 3 failures in an 80 piece sample. Maxim performs failure analysis on any lot that exceeds this reliability control level. Attached Burn-In Schematic (Spec. # 06-5036) shows the static Burn-In circuit. Maxim also performs quarterly 1000 hour life test monitors. This data is published in the Product Reliability Report (**RR-1M**).

### B. Moisture Resistance Tests

Maxim pulls pressure pot samples from every assembly process three times per week. Each lot sample must meet an LTPD = 20 or less before shipment as standard product. Additionally, the industry standard 85°C/85%RH testing is done per generic device/package family once a quarter.

### C. E.S.D. and Latch-Up Testing

The RS19 die type has been found to have all pins able to withstand a transient pulse of  $\pm 2000\text{V}$ , per Mil-Std-883 Method 3015 (reference attached ESD Test Circuit). Latch-Up testing has shown that this device withstands a current of  $\pm 100\text{mA}$  and/or  $\pm 20\text{V}$ .

**Table 1**  
Reliability Evaluation Test Results

**MAX253xxA**

<b>TEST ITEM</b>	<b>TEST CONDITION</b>	<b>FAILURE IDENTIFICATION</b>	<b>PACKAGE</b>	<b>SAMPLE SIZE</b>	<b>NUMBER OF FAILURES</b>
<b>Static Life Test</b> (Note 1)					
	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality		240	0
<b>Moisture Testing</b> (Note 2)					
Pressure Pot	Ta = 121°C P = 15 psi. RH= 100% Time = 168hrs.	DC Parameters & functionality	PDIP	77	0
			SO	77	0
			uMAX	77	0
85/85	Ta = 85°C RH = 85% Biased Time = 1000hrs.	DC Parameters & functionality		77	0
<b>Mechanical Stress</b> (Note 2)					
Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters		77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.

Note 2: Generic Package/Process data

Attachment #1

TABLE II. Pin combination to be tested. 1/ 2/

	Terminal A (Each pin individually connected to terminal A with the other floating)	Terminal B (The common combination of all like-named pins connected to terminal B)
1.	All pins except $V_{PS1}$ 3/	All $V_{PS1}$ pins
2.	All input and output pins	All other input-output pins

1/ Table II is restated in narrative form in 3.4 below.

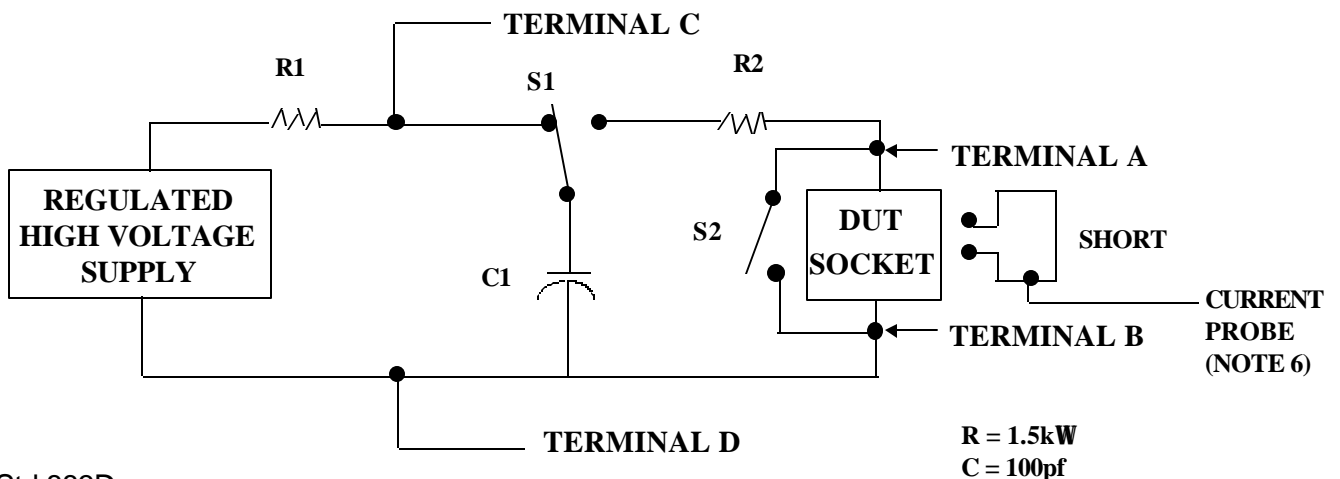
2/ No connects are not to be tested.

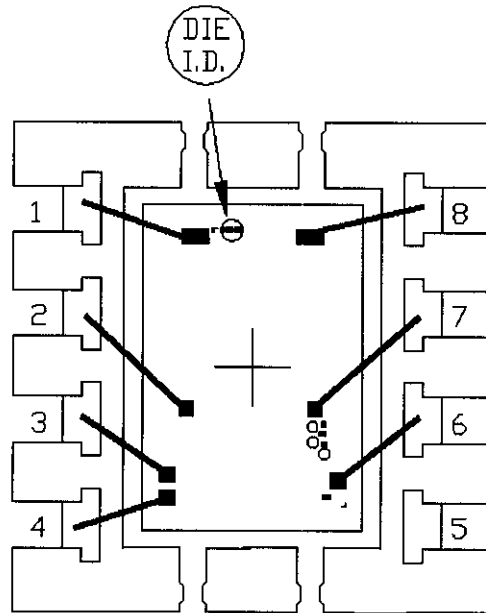
3/ Repeat pin combination 1 for each named Power supply and for ground

(e.g., where  $V_{PS1}$  is  $V_{DD}$ ,  $V_{CC}$ ,  $V_{SS}$ ,  $V_{BB}$ , GND,  $+V_S$ ,  $-V_S$ ,  $V_{REF}$ , etc).

3.4 Pin combinations to be tested.

- a. Each pin individually connected to terminal A with respect to the device ground pin(s) connected to terminal B. All pins except the one being tested and the ground pin(s) shall be open.
- b. Each pin individually connected to terminal A with respect to each different set of a combination of all named power supply pins (e.g.,  $V_{SS1}$ , or  $V_{SS2}$  or  $V_{SS3}$  or  $V_{CC1}$ , or  $V_{CC2}$ ) connected to terminal B. All pins except the one being tested and the power supply pin or set of pins shall be open.
- c. Each input and each output individually connected to terminal A with respect to a combination of all the other input and output pins connected to terminal B. All pins except the input or output pin being tested and the combination of all the other input and output pins shall be open.





PKG.CODE: U8-1

APPROVALS

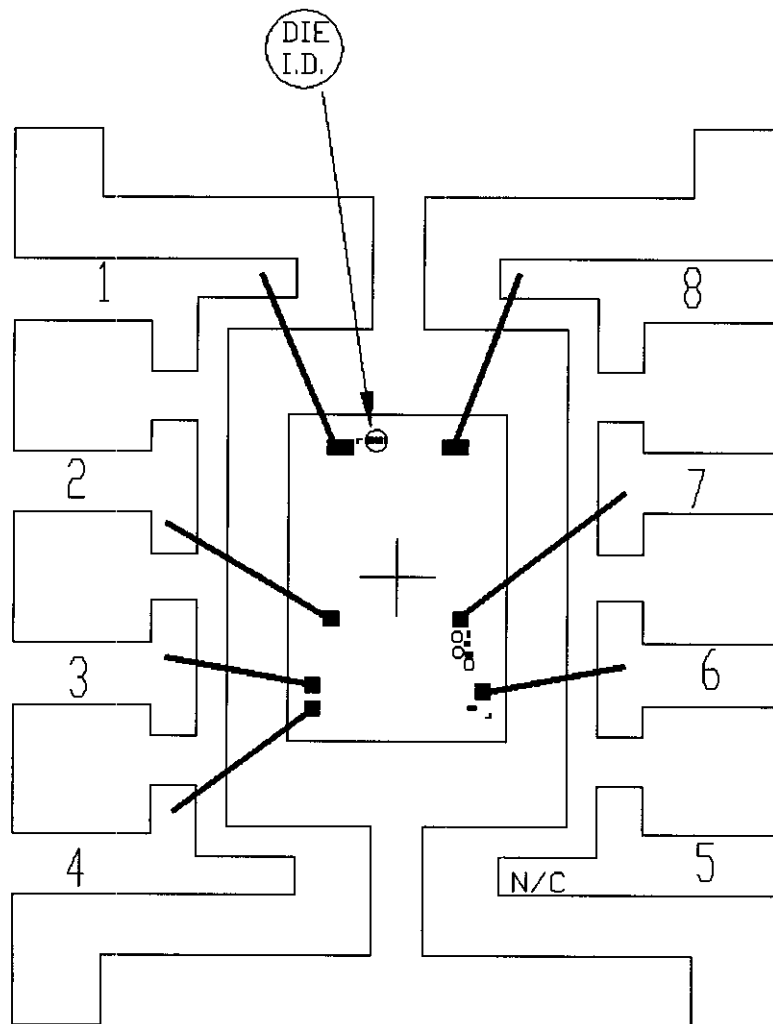
DATE



CAV./PAD SIZE:  
68X94

PKG.  
DESIGN

BUILDSHEET NUMBER: 05-1901-0046	REV.: B
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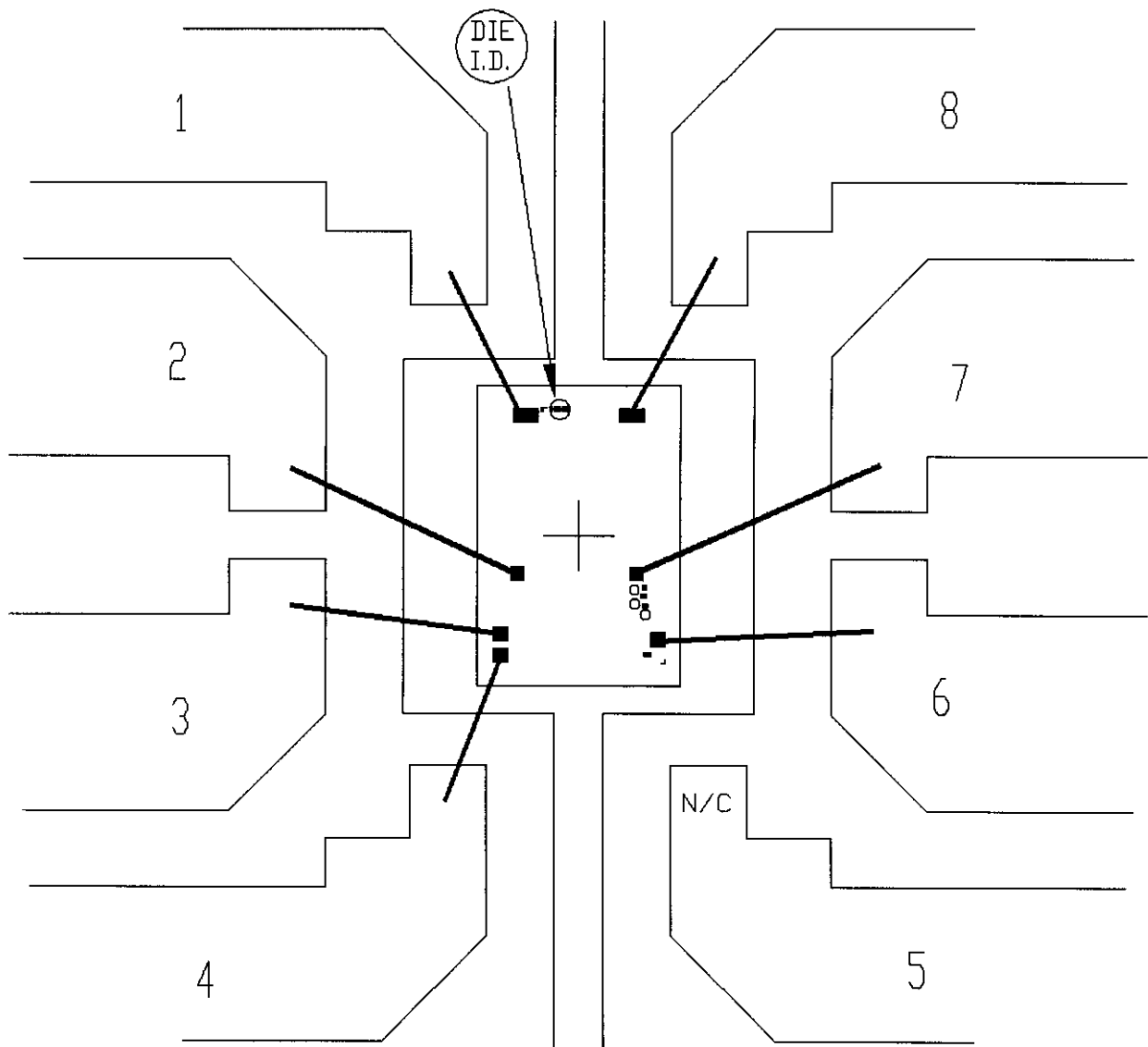


PKG.CODE: S8-4	
CAV./PAD SIZE: 90 X 130	PKG. DESIGN

APPROVALS

DATE

<b>MAXIM</b>	
BUILDSHEET NUMBER: 05-1901-0044	REV: B



PKG.CODE: P8-1

CAV./PAD SIZE:  
100 X 100

PKG.  
DESIGN

APPROVALS

DATE

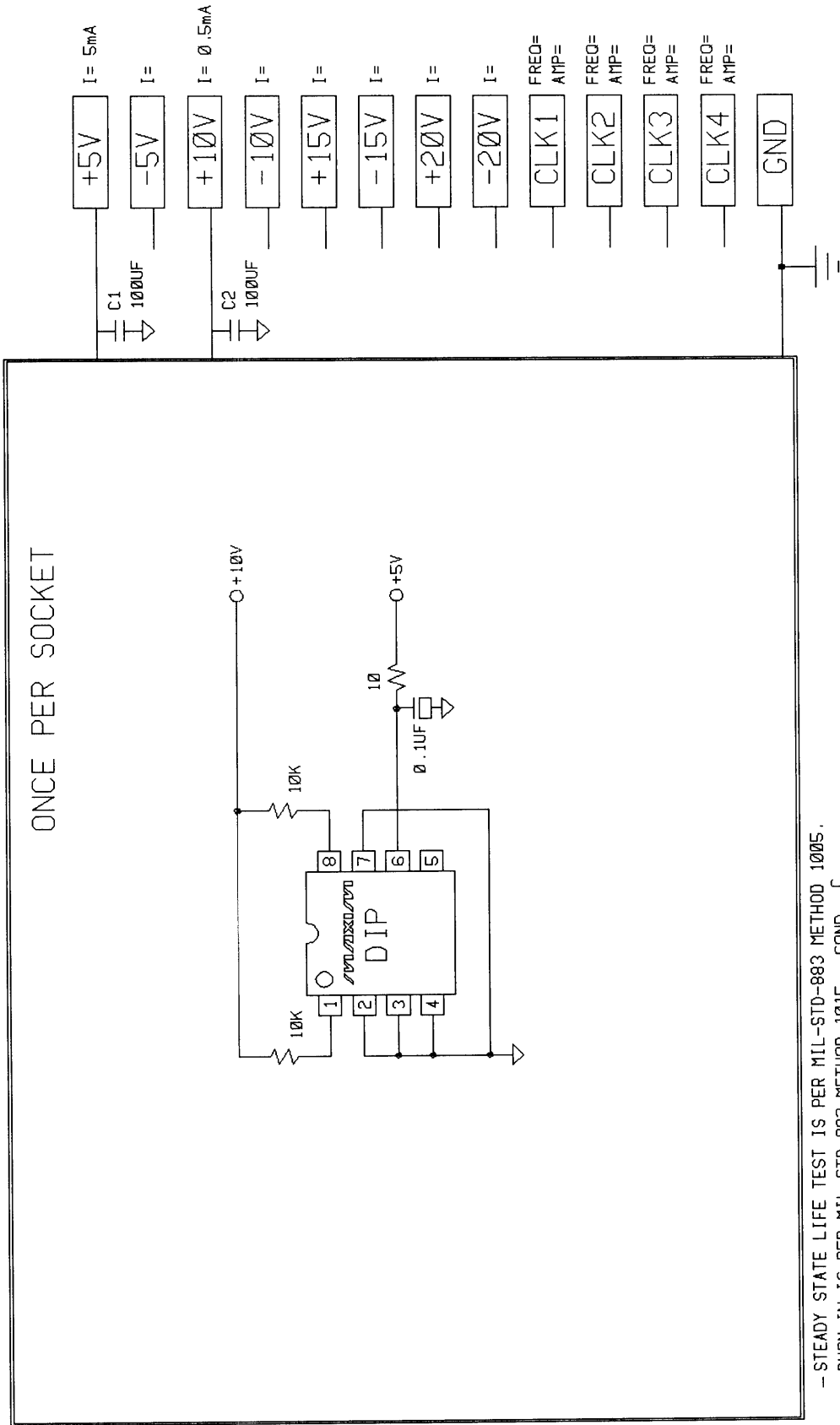
**MAXIM**

BUILDSHEET NUMBER:  
05-1901-0043

REV.:  
B

ONCE PER BOARD

ONCE PER SOCKET



- STEADY STATE LIFE TEST IS PER MIL-STD-883 METHOD 1005.  
 - BURN-IN IS PER MIL-STD-883 METHOD 1015. COND. C

NOTES :

1. TEMPERATURE : 125C OR EQUIVALENT
2. TIME : 160 HOURS MIN. OR EQUIVALENT
3. ALL COMPONENTS AND MATERIAL MUST STAND 150C CONTINUOUS
4. APPROVED FOR [X] COMMERCIAL [X] HR/883

SPEC. NO. 06-5036 REV. B

DATE : 3/7/95

DRAWN BY :

MAXIM BURN-IN SCHEMATIC

DEVICE TYPE :

MAX253/845